

## LMV7231 Hex Window Comparator with 1.5% Precision and 400mV Reference

Check for Samples: [LMV7231](#)

### FEATURES

- (For  $V_S = 3.3V \pm 10\%$ , Typical unless otherwise noted)
- High accuracy voltage reference: 400 mV
- Threshold Accuracy:  $\pm 1.5\%$  (max)
- Wide supply voltage range +2.2V to +5.5V
- Input/Output voltage range above  $V+$
- Internal hysteresis: 6mV
- Propagation delay: 2.6  $\mu s$  to 5.6  $\mu s$
- Supply Current 7.7  $\mu A$  per channel

- 24 lead LLP package
- Temperature range:  $-40^\circ C$  to  $125^\circ C$

### APPLICATIONS

- Power Supply Voltage Detection
- Battery Monitoring
- Handheld Instruments
- Relay Driving
- Industrial Control Systems

### DESCRIPTION

The LMV7231 is a 1.5% accurate Hex Window Comparator which can be used to monitor power supply voltages. The device uses an internal 400mV reference for the comparator trip value. The comparator set points can be set via external resistor dividers. The LMV7231 has 6 outputs (CO1-CO6) that signal an under-voltage or over-voltage event for each power supply input. An output (AO) is also provided to signal when any of the power supply inputs have an over-voltage or under-voltage event. This ability to signal an under-voltage or over-voltage event for the individual power supply inputs, in addition to an output to signal such an event on any of the power supply inputs adds unparallelled system protection capability.

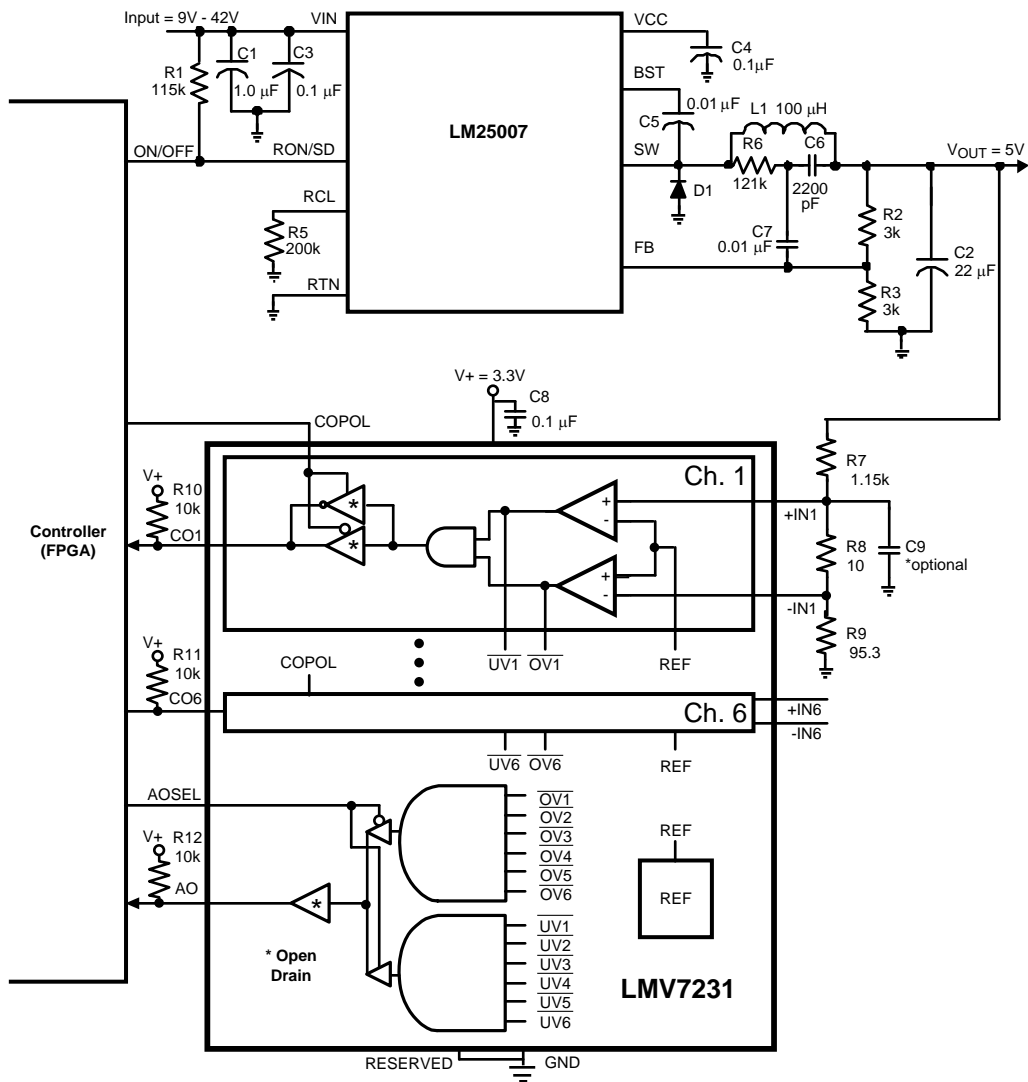
The LMV7231's +2.2V to +5.5V power supply voltage range, low supply current, and input/output voltage range above  $V+$  make it ideal for a wide range of power supply monitoring applications. Operation is guaranteed over the  $-40^\circ C$  to  $+125^\circ C$  temperature range. The device is available in a 24-pin LLP package.



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Typical Application Circuit



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

### Absolute Maximum Ratings <sup>(1)</sup>

ESD Tolerance <sup>(2)</sup>	
Human Body Model	2000V
Machine Model	200V
Supply Voltage	6V
Voltage at Input/Output Pin	6V to (GND – 0.3V)
Output Current	10mA
Total Package Current	50mA
Storage Temp Range	–65°C to +150°C
Junction Temperature <sup>(3)</sup>	150°C
For soldering specifications: see product folder at <a href="http://www.national.com">www.national.com</a> and <a href="http://www.national.com/ms/MS/MS-SOLDERING.pdf">www.national.com/ms/MS/MS-SOLDERING.pdf</a>	

- (1) *Absolute Maximum Ratings* indicate limits beyond which damage to the device may occur. *Operating Ratings* indicate conditions for which the device is intended to be functional, but specific performance is not guaranteed. For guaranteed specifications and the test conditions, see the *Electrical Characteristics*.
- (2) Human Body Model, applicable std. MIL-STD-883, Method 3015.7. Machine Model, applicable std. JESD22-A115-A (ESD MM std. of JEDEC) Field-Induced Charge-Device Model, applicable std. JESD22-C101-C (ESD FICDM std. of JEDEC).
- (3) The maximum power dissipation is a function of  $T_{J(MAX)}$ ,  $\theta_{JA}$ . The maximum allowable power dissipation at any ambient temperature is  $P_D = (T_{J(MAX)} - T_A) / \theta_{JA}$ . All numbers apply for packages soldered directly onto a PC board.

### Operating Ratings <sup>(1)</sup>

Supply Voltage	2.2V to 5.5V
Junction Temperature Range <sup>(2)</sup>	–40°C to +125°C
Package Thermal Resistance, $\theta_{JA}$	
24 Lead LLP	38°C/W

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- (2) The maximum power dissipation is a function of  $T_{J(MAX)}$ ,  $\theta_{JA}$ . The maximum allowable power dissipation at any ambient temperature is  $P_D = (T_{J(MAX)} - T_A) / \theta_{JA}$ . All numbers apply for packages soldered directly onto a PC board.

### +3.3V Electrical Characteristics

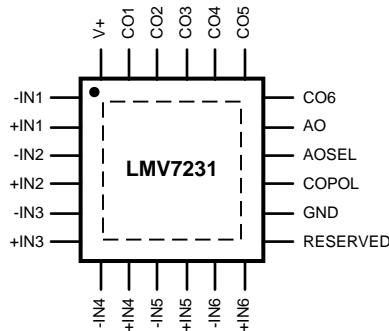
Unless otherwise specified, all limits guaranteed for  $T_A = 25^\circ\text{C}$ ,  $V_+ = 3.3\text{V} \pm 10\%$ ,  $\text{GND} = 0\text{V}$ , and  $R_L > 1\text{M}\Omega$ . **Boldface limits apply for  $T_A = -10^\circ\text{C}$  to  $+70^\circ\text{C}$ .**

Symbol	Parameter	Condition	Min (1)	Typ (2)	Max (1) ns	Units
$V_{\text{THR}}$	Threshold: Input Rising	$R_L = 10\text{k}\Omega$	394 <b>391.4</b>	400	406 <b>408.6</b>	mV
$V_{\text{THF}}$	Threshold: Input Falling	$R_L = 10\text{k}\Omega$	386 <b>383.8</b>	394	401 <b>403.2</b>	mV
$V_{\text{HYST}}$	Hysteresis ( $V_{\text{THR}} - V_{\text{THF}}$ )	$R_L = 10\text{k}\Omega$	3.9	6.0	8.8	mV
$I_{\text{BIAS}}$	Input Bias Current	$V_{\text{IN}} = V_+$ , GND, and 5.5V	-5 <b>-15</b>	0.05	5 <b>15</b>	nA
$V_{\text{OL}}$	Output Low Voltage	$I_L = 5\text{mA}$		160	200 <b>250</b>	mV
$I_{\text{OFF}}$	Output Leakage Current	$V_{\text{OUT}} = V_+$ , 5.5V and 40mV of overdrive			0.4 <b>1</b>	$\mu\text{A}$
$t_{\text{PDHL1}}$	High-to-Low Propagation Delay (+IN falling)	10mV of overdrive		2.6	6	$\mu\text{s}$
$t_{\text{PDHL2}}$	High-to-Low Propagation Delay (-IN rising)	10mV of overdrive		5.4	10	$\mu\text{s}$
$t_{\text{PDLH1}}$	Low-to-High Propagation Delay (+IN rising)	10mV of overdrive		5.6	10	$\mu\text{s}$
$t_{\text{PDLH2}}$	Low-to-High Propagation Delay (-IN falling)	10mV of overdrive		2.8	6	$\mu\text{s}$
$t_r$	Output Rise Time	$C_L = 10\text{pF}$ , $R_L = 10\text{k}\Omega$		0.5		$\mu\text{s}$
$t_f$	Output Fall Time	$C_L = 100\text{pF}$ , $R_L = 10\text{k}\Omega$			0.25 <b>0.3</b>	$\mu\text{s}$
$I_{\text{IN}(1)}$	Digital Input Logic "1" Leakage Current				0.2 <b>1</b>	$\mu\text{A}$
$I_{\text{IN}(0)}$	Digital Input Logic "0" Leakage Current				0.2 <b>1</b>	$\mu\text{A}$
$V_{\text{IH}}$	Digital Input Logic "1" Voltage		<b><math>0.70 \times V_+</math></b>			V
$V_{\text{IL}}$	Digital Input Logic "0" Voltage				<b><math>0.30 \times V_+</math></b>	V
$I_S$	Power Supply Current	No loading (outputs high)		46	60 <b>84</b>	$\mu\text{A}$
$V_{\text{THPSS}}$	$V_{\text{TH}}$ Power Supply Sensitivity (3)	$V_+$ Ramp Rate = 1.1ms $V_+$ Step = 2.5V to 4.5V			+400	$\mu\text{V}$
		$V_+$ Ramp Rate = 1.1ms $V_+$ Step = 4.5V to 2.5V	-400			$\mu\text{V}$

- (1) Limits are 100% production tested at  $25^\circ\text{C}$ . Limits over the operating temperature range are guaranteed through correlations using the Statistical Quality Control (SQC) method.
- (2) Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration. The typical values are not tested and are not guaranteed on shipped production material.
- (3)  $V_{\text{TH}}$  Power Supply Sensitivity is defined as the temporary shift in the internal voltage reference due to a step on the  $V_+$  pin.

## Connection Diagram

Figure 1. 24-Pin LLP Package (Top View)



## Pin Functions

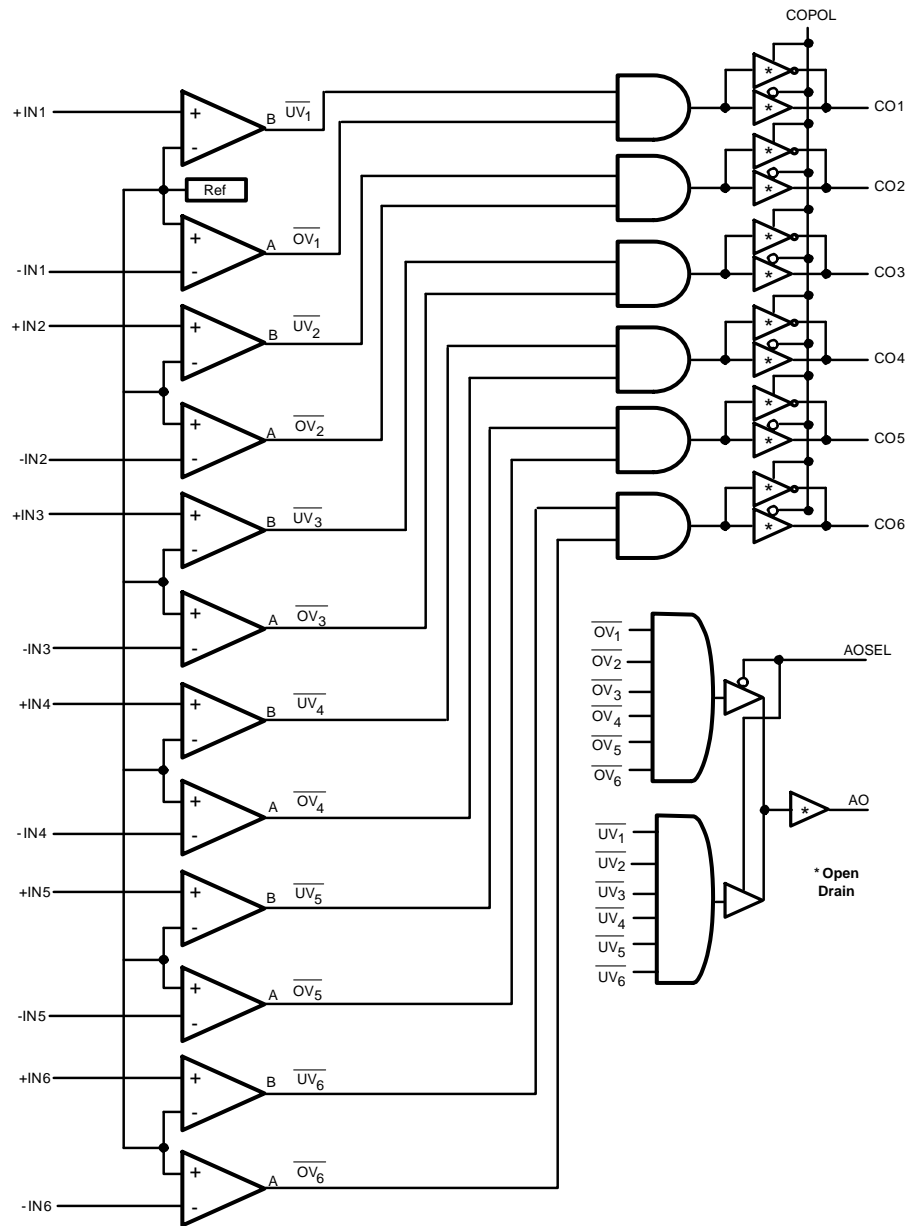
### Pin Descriptions

Pin	Symbol	Type	Description
1	-IN1	Analog Input	Negative input for window comparator 1.
2	+IN1	Analog Input	Positive input for window comparator 1.
3	-IN2	Analog Input	Negative input for window comparator 2.
4	+IN2	Analog Input	Positive input for window comparator 2.
5	-IN3	Analog Input	Negative input for window comparator 3.
6	+IN3	Analog Input	Positive input for window comparator 3.
7	-IN4	Analog Input	Negative input for window comparator 4.
8	+IN4	Analog Input	Positive input for window comparator 4.
9	-IN5	Analog Input	Negative input for window comparator 5.
10	+IN5	Analog Input	Positive input for window comparator 5.
11	-IN6	Analog Input	Negative input for window comparator 6.
12	+IN6	Analog Input	Positive input for window comparator 6.
13	RESERVED	Digital Input	Connect to GND.
14	GND	Power	Ground reference pin for the power supply voltage.
15	COPOL	Digital Input	The state of this pin determines whether the CO1-CO6 pins are active "HIGH" or "LOW". When tied LOW the CO1-CO6 outputs will go LOW to indicate an out of window comparison.
16	AOSEL	Digital Input	The state of this pin determines whether the AO pin is active on an over-voltage or under-voltage event. When tied LOW the AO output will be active upon an over-voltage event.
17	AO	Open-Drain NMOS Digital Output	This output is the ANDED combination of either the over-voltage comparator outputs or the under-voltage comparator outputs and is controlled by the state of the AOSEL. AO pin is active "LOW".
18	CO6	Open-Drain NMOS Digital Output	Window comparator 6 NMOS open-drain output.
19	CO5	Open-Drain NMOS Digital Output	Window comparator 5 NMOS open-drain output.
20	CO4	Open-Drain NMOS Digital Output	Window comparator 4 NMOS open-drain output.
21	CO3	Open-Drain NMOS Digital Output	Window comparator 3 NMOS open-drain output.
22	CO2	Open-Drain NMOS Digital Output	Window comparator 2 NMOS open-drain output.
23	CO1	Open-Drain NMOS Digital Output	Window comparator 1 NMOS open-drain output.

**Pin Descriptions (continued)**

Pin	Symbol	Type	Description
24	V+	Power	Power supply pin.
DAP	DAP	Thermal Pad	Die Attach Paddle (DAP) connect to GND.

Block Diagram

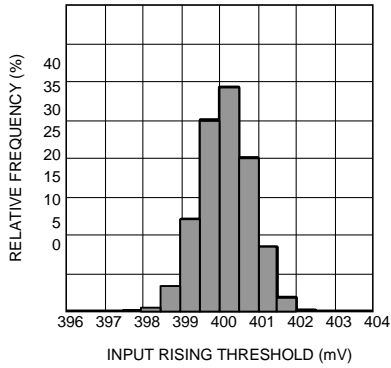


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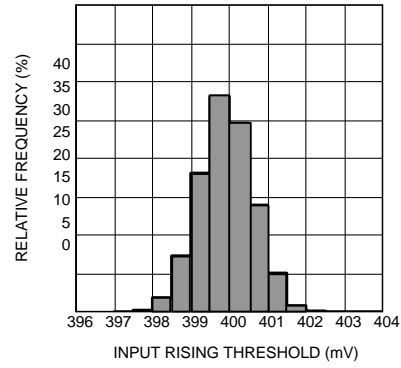
### Typical Performance Characteristics

$V^+ = 3.3V$  and  $T_A = 25^\circ C$  unless otherwise noted.

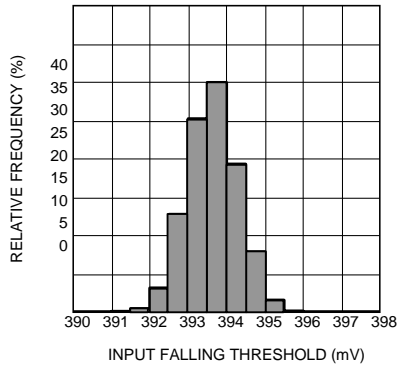
**+In Input Rising Threshold Distribution**



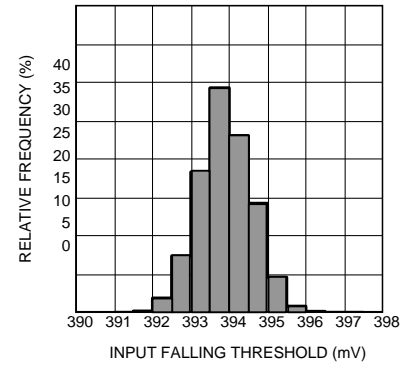
**-In Input Rising Threshold Distribution**



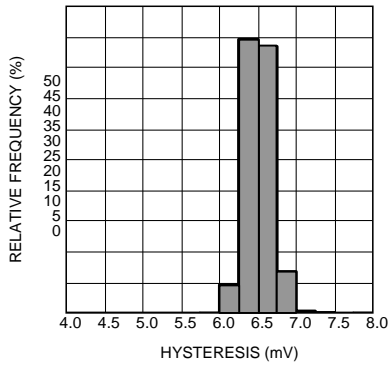
**+In Input Falling Threshold Distribution**



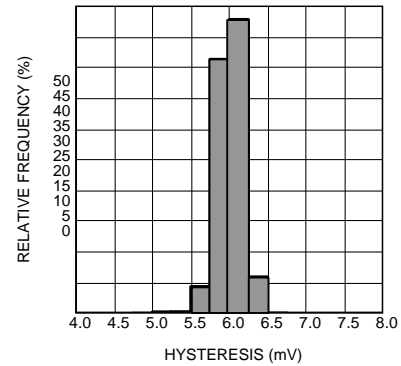
**-In Input Falling Threshold Distribution**



**+In Hysteresis Distribution**



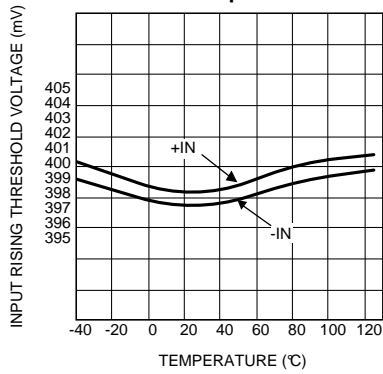
**-In Hysteresis Distribution**



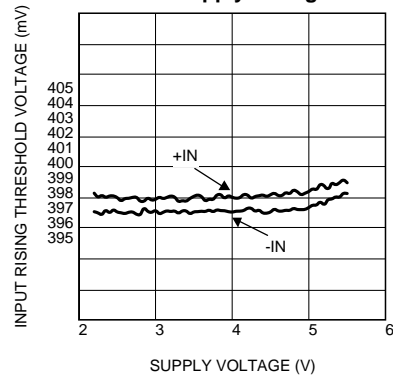
Typical Performance Characteristics (continued)

V<sup>+</sup> = 3.3V and T<sub>A</sub> =25°C unless otherwise noted.

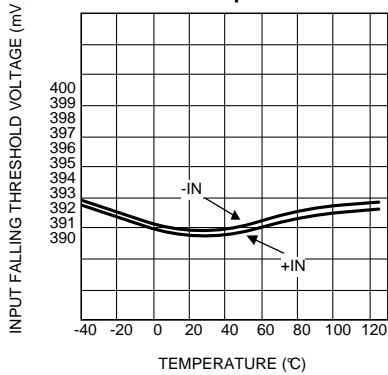
Input Rising Threshold Voltage vs. Temperature



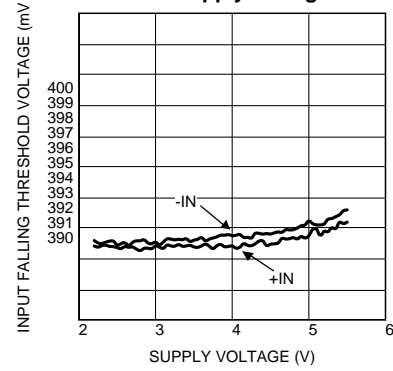
Input Rising Threshold Voltage vs. Supply Voltage



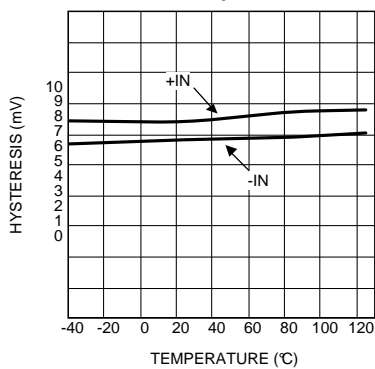
Input Falling Threshold Voltage vs. Temperature



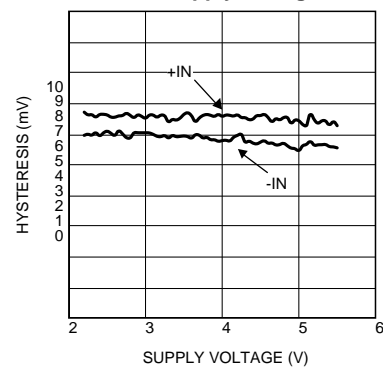
Input Falling Threshold Voltage vs. Supply Voltage



Hysteresis vs. Temperature



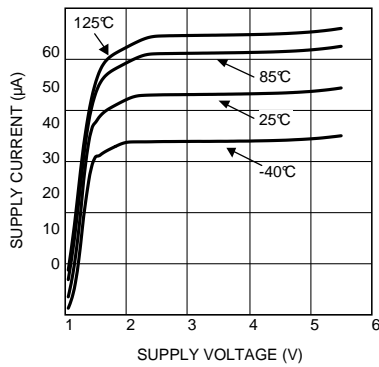
Hysteresis vs. Supply Voltage



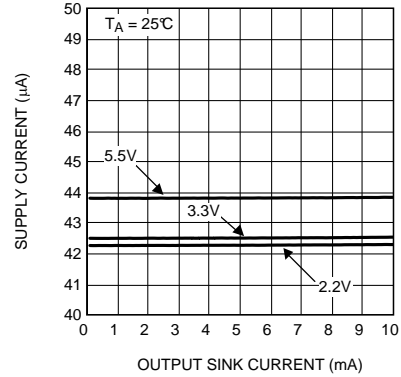
### Typical Performance Characteristics (continued)

V<sup>+</sup> = 3.3V and T<sub>A</sub> = 25°C unless otherwise noted.

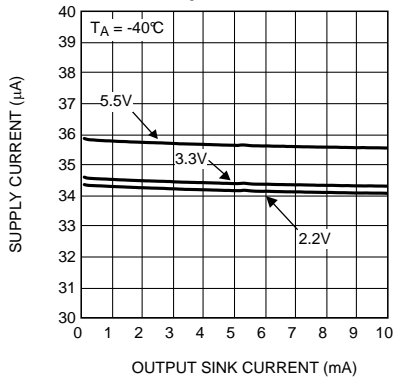
**Supply Current vs. Supply Voltage and Temperature**



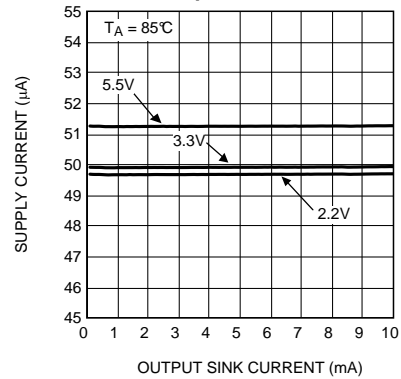
**Supply Current vs. Output Sink Current**



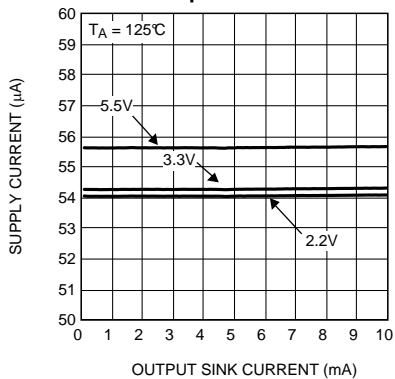
**Supply Current vs. Output Sink Current**



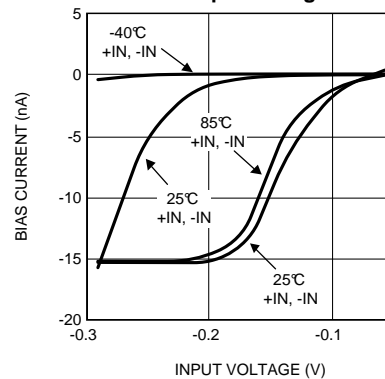
**Supply Current vs. Output Sink Current**



**Supply Current vs. Output Sink Current**



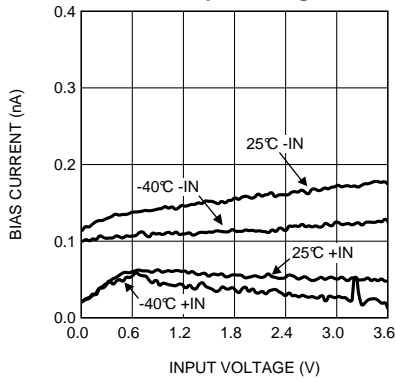
**Bias Current vs. Input Voltage**



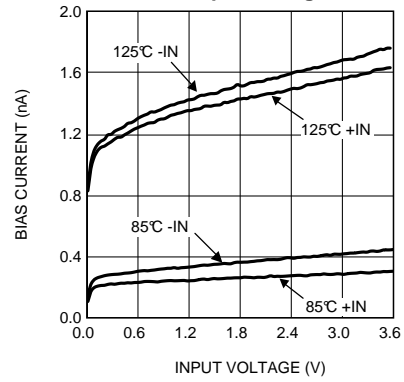
**Typical Performance Characteristics (continued)**

$V^+ = 3.3V$  and  $T_A = 25^\circ C$  unless otherwise noted.

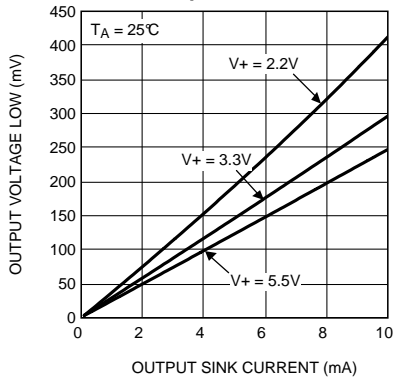
**Bias Current vs. Input Voltage**



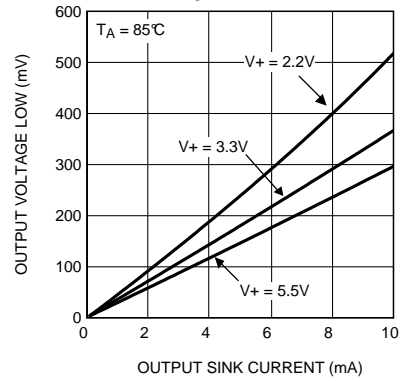
**Bias Current vs. Input Voltage**



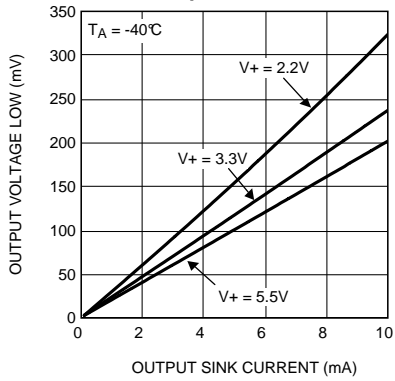
**Output Voltage Low vs. Output Sink Current**



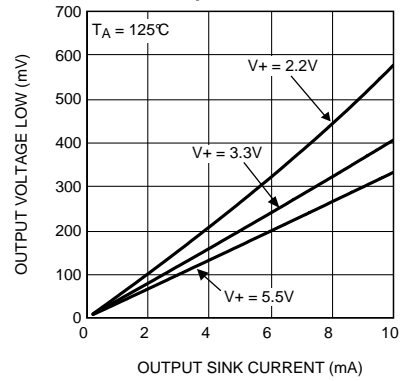
**Output Voltage Low vs. Output Sink Current**



**Output Voltage Low vs. Output Sink Current**



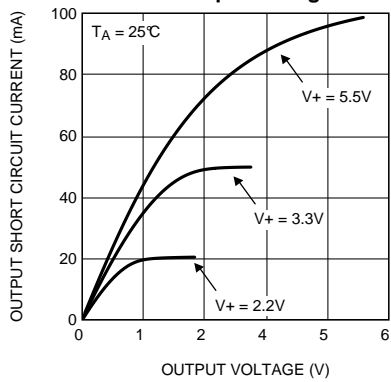
**Output Voltage Low vs. Output Sink Current**



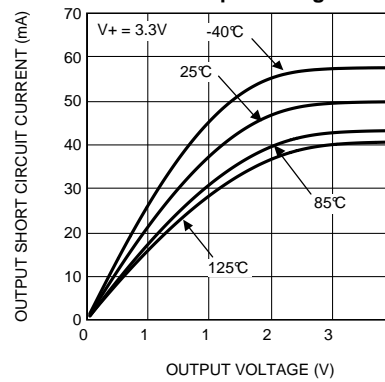
### Typical Performance Characteristics (continued)

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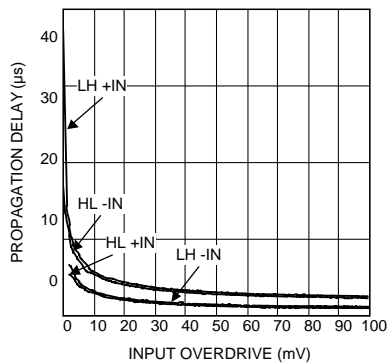
**Output Short Circuit Current vs. Output Voltage**



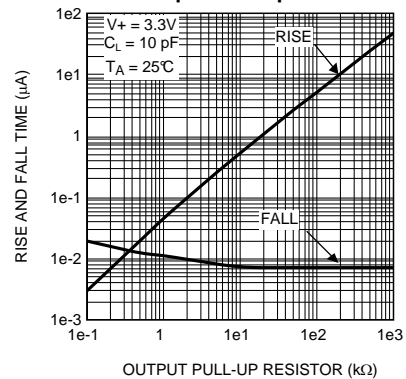
**Output Short Circuit Current vs. Output Voltage**



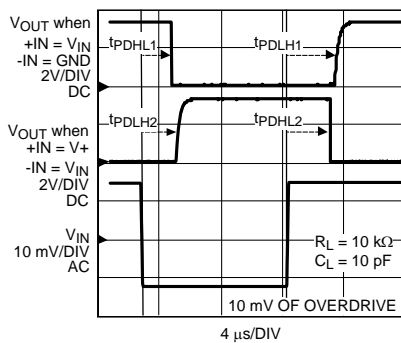
**Propagation Delay vs. Input Overdrive**



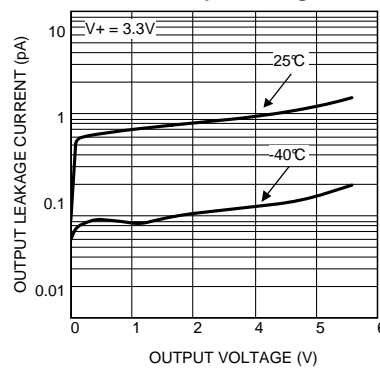
**Rise and Fall Times vs. Output Pull-Up Resistor**



**Propagation Delay**

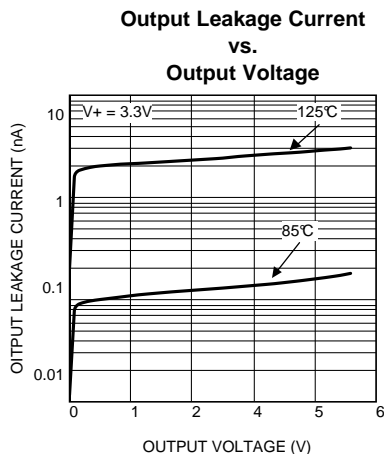


**Output Leakage Current vs. Output Voltage**



### Typical Performance Characteristics (continued)

$V^+ = 3.3V$  and  $T_A = 25^\circ C$  unless otherwise noted.



### Application Information

#### RESISTOR VOLTAGE DIVIDER SELECTION

The LMV7231 trip points can be set by external resistor dividers as shown in [Figure 2](#)

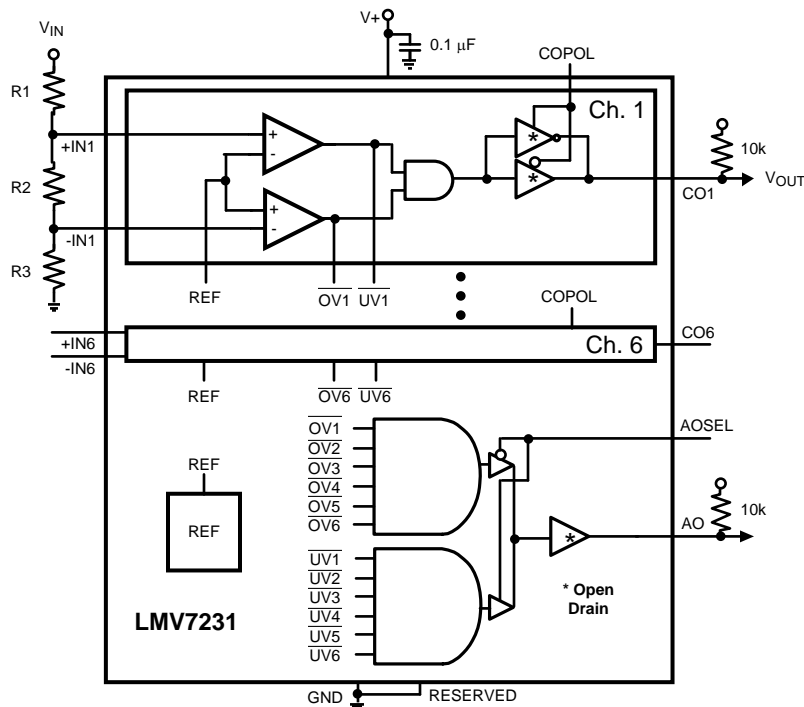
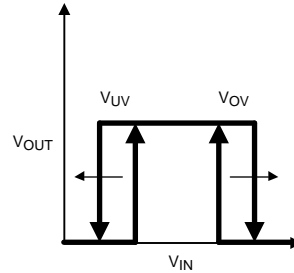


Figure 2. External Resistor Dividers

Each trip point, over-voltage,  $V_{OV}$ , and under-voltage,  $V_{UV}$ , can be optimized for a falling supply,  $V_{THF}$ , or a rising supply,  $V_{THR}$ . Therefore there are  $2^2 = 4$  different optimization cases. Exiting the voltage detection window ([Figure 3](#)), entering the window ([Figure 4](#)), rising into and out of the window ([Figure 5](#)), falling into and out of the window ([Figure 6](#)). Note that for each case each trip point can be optimized for either a rising or falling signal, not both. The governing equations make it such that if the same resistor, R3, and over/under-voltage ratio,  $V_{OV}/V_{UV}$ , is used across the channels the same nominal current will travel through the resistor ladder. As a result R2 will also be the same across channels and only R1 needs to change to set voltage detection window maximizing

reuse of resistor values and minimizing design complexity. Select the R3 resistor value to be below 100k $\Omega$  so the current through the divider ladder is much greater than the LMV7231 bias current. If the current traveling through the resistor divider is on the same magnitude of the LMV7231  $I_{BIAS}$ , the  $I_{BIAS}$  current will create error in your circuit and cause trip voltage shifts. Keep in mind the greatest error due to  $I_{BIAS}$  will be caused when that current passes through the greatest equivalent resistance,  $R_{EQ} = R1 \parallel (R2 + R3)$ , which will be seen by the positive input of the window comparator, +IN.



R3 set

$$R2 = R3((V_{THF}/V_{THR})V_{OV}/V_{UV} - 1)$$

$$R1 = R3((1/V_{THR})V_{OV} - (V_{THF}/V_{THR})V_{OV}/V_{UV})$$

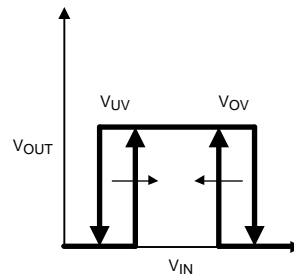
Ex.  $V_{OV} = 3.465V$ ,  $V_{UV} = 3.135V$ , i.e.  $V_{RANGE} = 3.3V \pm 5\%$

R3 set to 10 k $\Omega$

$$R2 = 10k((0.394/0.4)3.465/3.135 - 1) \approx 887\Omega$$

$$R1 = 10k((1/0.4)3.465 - (0.394/0.4)3.465/3.135) \approx 75\text{ k}\Omega$$

**Figure 3. Exiting the Voltage Detection Window**



R3 set

$$R2 = R3((V_{THR}/V_{THF})V_{OV}/V_{UV} - 1)$$

$$R1 = R3((1/V_{THF})V_{OV} - (V_{THR}/V_{THF})V_{OV}/V_{UV})$$

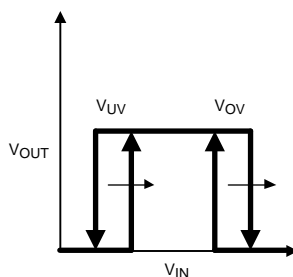
Ex.  $V_{OV} = 3.465V$ ,  $V_{UV} = 3.135V$ , i.e.  $V_{RANGE} = 3.3V \pm 5\%$

R3 set to 10 k $\Omega$

$$R2 = 10k((0.4/0.394)3.465/3.135 - 1) \approx 1.21\text{ k}\Omega$$

$$R1 = 10k((1/0.394)3.465 - (0.4/0.394)3.465/3.135) \approx 76.8\text{ k}\Omega$$

**Figure 4. Entering the Voltage Detection Window**



R3 set

$$R2 = R3(V_{OV}/V_{UV} - 1)$$

$$R1 = R3((1/V_{THR})V_{OV} - V_{OV}/V_{UV})$$

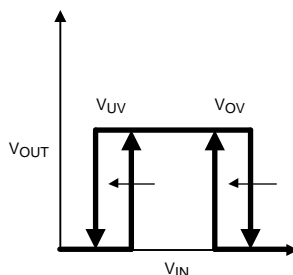
Ex.  $V_{OV} = 3.465V$ ,  $V_{UV} = 3.135V$ , i.e.  $V_{RANGE} = 3.3V \pm 5\%$

R3 set to 10 k $\Omega$

$$R2 = 10k((3.465/3.135) - 1) \approx 1.05 \text{ k}\Omega$$

$$R1 = 10k((1/0.4)3.465 - 3.465/3.135) \approx 75 \text{ k}\Omega$$

Figure 5. Rising Into and Out Of the Voltage Detection Window



R3 set

$$R2 = R3(V_{OV}/V_{UV} - 1)$$

$$R1 = R3((1/V_{THF})V_{OV} - V_{OV}/V_{UV})$$

Ex.  $V_{OV} = 3.465V$ ,  $V_{UV} = 3.135V$ , i.e.  $V_{RANGE} = 3.3V \pm 5\%$

R3 set to 10 k $\Omega$

$$R2 = 10k((3.465/3.135) - 1) \approx 1.05 \text{ k}\Omega$$

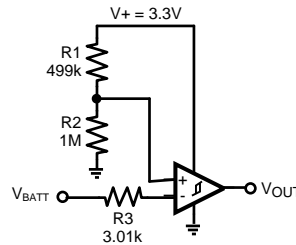
$$R1 = 10k((1/0.394)3.465 - 3.465/3.135) \approx 76.8 \text{ k}\Omega$$

Figure 6. Falling Into and Out Of the Voltage Detection Window

### INPUT/OUTPUT VOLTAGE RANGE ABOVE V+

The LMV7231 Hex Window Comparator with 1.5% precision can accurately monitor up to 6 power rails or batteries at one time. The input and output voltages of the device can exceed the supply voltage, V+, of the comparator, and can be up to the absolute maximum ratings without causing damage or performance degradation. The typical  $\mu C$  input pin with crowbar diode ESD protection circuitry will not allow the input to go above V+, and thus its usefulness is limited in power supply supervision applications.

The supply independent inputs of the window comparator blocks allow the LMV7231 to be tolerant of system faults. For example if the power is suddenly removed from the LMV7231 due to a system malfunction yet there still exists a voltage on the input, this will not be an issue as long as the monitored input voltage does not exceed absolute maximum ratings. Another example where this feature comes in handy is a battery sense application such as the one in [Figure 7](#). The boards may be sitting on the shelf unbiased with V+ grounded, and yet have a fully charged battery on board. If the comparator measuring the battery had crowbar diodes, the diode from –IN to V+ would turn on, sourcing current from the battery eventually draining the battery. However, when using the LMV7231 no current, except the low input bias current of the device, will flow into the chip, and the battery charge will be preserved.



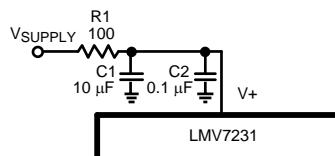
**Figure 7. Battery Sense Application**

The output pin voltages of the device can also exceed the supply voltage, V+, of the comparator. This provides extra flexibility and enables designs which pull up the outputs to higher voltage levels to meet system requirements. For example it's possible to run the LMV7231 at its minimum operating voltage, V+ = +2.2V, but pull up the output up to the absolute maximum ratings to bias a blue LED, with a forward voltage of V<sub>F</sub> = +4V.

In a power supply supervision application the hardwired LMV7231 is a sound solution compared to the uC with software alternative for several reasons. First, startup is faster. During startup you don't need to account for code loading time, oscillator ramp time, and reset time. Second, operation is quick. The LMV7231 has a maximum propagation delay in the μs and isn't affected by sampling and conversion delays related to reading data, calculating data, and setting flags. Third, less overhead. The LMV7231 doesn't require an expensive power consuming microcontroller nor is it dependent on controller code which could get damaged or crash.

### POWER SUPPLY BYPASSING

Bypass the supply pin, V+, with a 0.1 μF ceramic capacitor placed close to the V+ pin. If transients with rise/fall times of 100's μs and magnitudes of 100's mV are expected on the power supply line a RC low pass filter network as shown in [Figure 8](#) is recommended for additional bypassing. If no such bypass network is used power supply transients can cause the internal voltage reference of the comparator to temporarily shift potentially resulting in a brief incorrect comparator output. For example if an RC network with 100Ω resistance and 10μF capacitance (1.1ms rise time) is used the voltage reference will shift temporarily the amount, V<sub>TH</sub> Power Supply Sensitivity (V<sub>TH</sub>PSS), specified in the Electrical Characteristics table.



**Figure 8. Power Supply Bypassing**

### POWER SUPPLY SUPERVISION

[Figure 9](#) shows a power supply supervision circuit utilizing the LMV7231. This application uses the efficient, easy to use LM25007 step-down switching regulator. This switching regulator can handle a 9V – 42V input voltage range and it's regulated output voltage is set to 5V with R<sub>2</sub> = R<sub>3</sub> = 3kΩ.

$$V_{OUT} = 2.5 \times (R_2 + R_3)/R_3$$

$$= 2.5 \times (3k + 3k)/3k = 5V$$

(1)

Resistor R6 and capacitors C6, C7 are utilized to minimize output ripple voltage per the LM25007 evaluation board application note.

The comparator voltage window is set to 5V +/- 5% by R7=1.15kΩ , R8=10Ω, R9=95.3Ω. See [RESISTOR VOLTAGE DIVIDER SELECTION](#) section in the Application Information section of the datasheet for details on how to set the comparator voltage window.

With components selected the output ripple voltage seen on the LM25007 is approximately 30 - 35mV and is reduced to about 4mV at the comparator input, +IN1, by the resistor divider. This ripple voltage can be reduced multiple ways. First, user can operate the device in continuous conduction mode rather than discontinuous conduction mode. To do this increase the load current of the device (see LM25007 datasheet for more details). However, make sure not to exceed the power rating of the resistors in the resistor ladder. Second, ripple can be reduced further with a bypass cap, C9, at the resistor divider. If desired a user can select a 1uF capacitor to achieve less than 3mV ripple at +IN1. However, there is a tradeoff and adding capacitance at this node will lower the system response time.

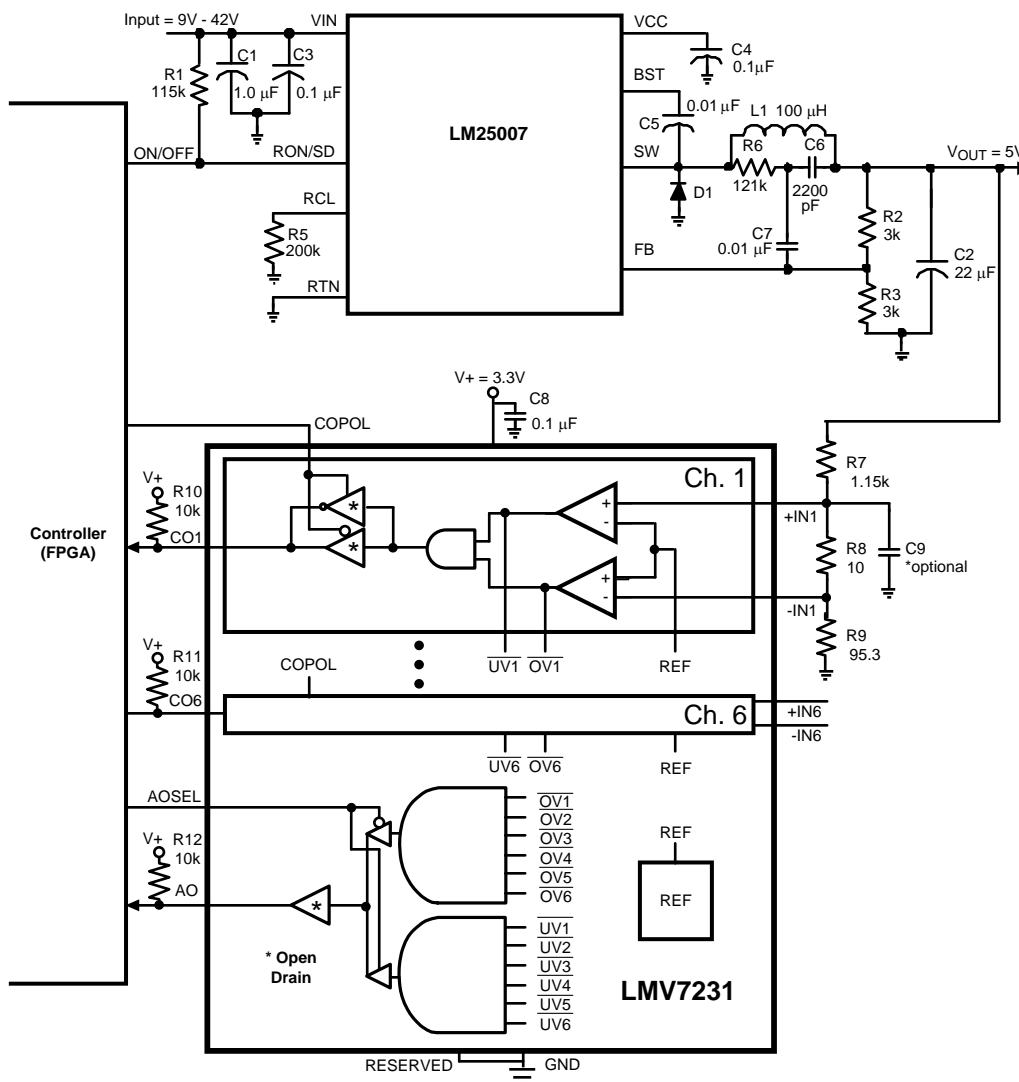


Figure 9. Power Supply Supervision

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
LMV7231SQ/NOPB	ACTIVE	WQFN	RTW	24	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	L7231SQ	<a href="#">Samples</a>
LMV7231SQE/NOPB	ACTIVE	WQFN	RTW	24	250	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	L7231SQ	<a href="#">Samples</a>
LMV7231SQX/NOPB	ACTIVE	WQFN	RTW	24	4500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	L7231SQ	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

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**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Only one of markings shown within the brackets will appear on the physical device.

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**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LMV7231SQ/NOPB	WQFN	RTW	24	1000	178.0	12.4	4.3	4.3	1.3	8.0	12.0	Q1
LMV7231SQE/NOPB	WQFN	RTW	24	250	178.0	12.4	4.3	4.3	1.3	8.0	12.0	Q1
LMV7231SQX/NOPB	WQFN	RTW	24	4500	330.0	12.4	4.3	4.3	1.3	8.0	12.0	Q1

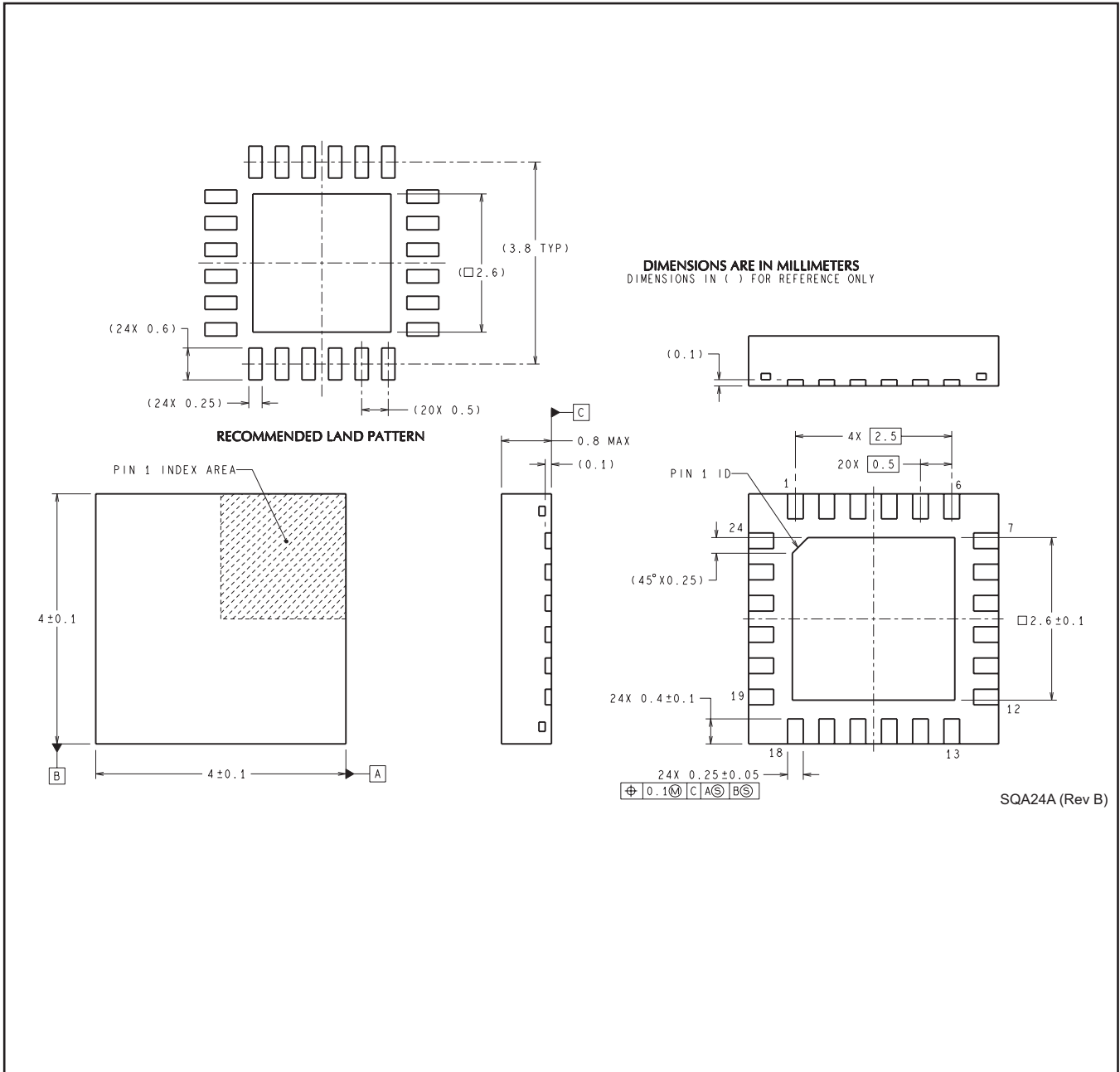
TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LMV7231SQ/NOPB	WQFN	RTW	24	1000	203.0	190.0	41.0
LMV7231SQE/NOPB	WQFN	RTW	24	250	203.0	190.0	41.0
LMV7231SQX/NOPB	WQFN	RTW	24	4500	349.0	337.0	45.0

RTW0024A



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